

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: Yoshihisa MATSUBARA, et al.

Filed: **Concurrently herewith**

For: METHOD FOR MANUFACTURING SEMICONDCUTOR....

Serial No.: **Concurrently herewith**

April 23, 2001

Assistant Commissioner of Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

SIR:

Prior to the issuance of an Office Action, please amend the application as follows:

IN THE CLAIMS

3. (Amended) A method according to claim 1, wherein said processing step is a cleaning step performed during, before and after a step that includes chemical mechanical polishing (CMP) for forming said wiring.

Please add the following new claim

12. (New) A method according to claim 2, wherein said processing step is a cleaning step performed during, before and after a step that includes chemical mechanical polishing (CMP) for forming said wiring.

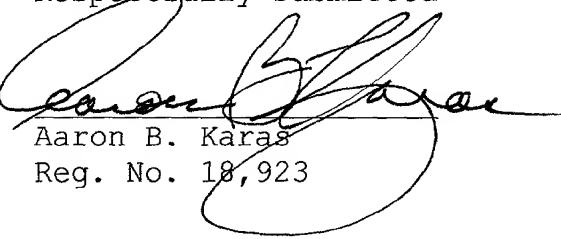
REMARKS

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page is captioned "Version with markings to show changes made."

This amendment is being submitted to avoid multiple dependent claims.

Favorable consideration is respectfully requested.

Respectfully submitted


Aaron B. Karas
Reg. No. 18,923

HELGOTT & KARAS, P.C.
60th FLOOR
EMPIRE STATE BUILDING
NEW YORK, NY 10118
DOCKET NO.: NEKA 18.612
BHU:PRELIM

VERSION WITH MARKINGS TO SHOW CHANGES MADE
IN THE CLAIMS

3. (Amended) A method according to claim 1 or 2, wherein said processing step is a cleaning step performed during, before and after a step that includes chemical mechanical polishing (CMP) for forming said wiring .